Two Part Silicone Potting (AA-2801 PA)

Technical Data Sheet

Product Description :

- Two component silicone addition type potting compound
- Low viscosity, good fluidity, easy to operate
- Glue can store a long time after mixing at room
- Temperature,It can be cured quickly under heating condition, especially for automatic production line
- Good temperature resistance, it can maintain rubber elasticity in a wide temperature range（-50 ～200℃）after cured.
- Good thermal conductivity, excellent insulation performance.
- The curing process does not shrink, has better
- waterproof and moisture resistance and anti-aging performance
- Comply with ROHS directive requirements.

Product Application :

- It can use in the high power electronic components, modular power supplies and circuit boards for potting protection, which has good heat conduction and temperature resistance. Such as LED driving power ,automotive HID lamp module power supply, automotive ignition system module power supply, network transformers, etc.

Product Instruction :

- Before use, the A component and B component in their respective containers fully mixing evenly and then according to the weight ratio of A:B=1:1, put into the mixing tank mixing evenly.
- Put the mixture into the container. Curing at room temperature or heating. In the winter, it will take a long time to cure, suggested by heating curing, curing under 80℃ for 15-30 minutes , and at room temperature, generally takes about 3~5 hours curing.

Caution :

- Glue should be sealed storage.
- This product is not dangerous, but do not eat and touch into the eyes.
- After a long period of storage, there will be precipitation in the glue. Please mix evenly to use. It does not affect the performance.
- Glue exposure to a certain amount of the following chemical substances will make the glue does not solidify: N, P, S organic compounds, Ionic compounds of Sn, Pb, Hg, As and other elements.

- Containing alkynes and vinyl compounds, in order to avoid the above phenomenon, the use of the circuit board as far as possible to wipe clean the remaining resin, try to use low lead content of solder. It can also use three anti - paint soaked, and then use glue.

Technical Specification (AA-2801 PA) -

component	A	B

AFTER MIXING @ 25℃, 65%RH

MIXING RATIO	A:B = 1:1
Viscosity (CP)	6900-7200
Curingtime @ 30℃	3-3.5 HOURS
Curingtime @ 80℃	15-18 MINUTES
Hardness	50-55 shoreA
Thermal Conductivity	1 W/m·K
Dielectric strength	6-9 kV/mm
Surface Dry Time	65-75 MINUTES

Packing Specification :

PART-A - 25Kg PART-B - 25Kg

Storage And Transport :

- Material should be Stored @ 25℃ - 30℃.
- Such products are non hazardous and can be transported in general chemicals.